

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L3 | 2 | 438/107,109,110,112,124,126,127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and ("c.sub.4") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:07 |
| L4 | 6 | "438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and ("c.sub.4") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:05 |
| L5 | 93 | "438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and ("c4") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:06 |
| L6 | 0 | ("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) with ("c4") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:06 |
| L7 | 0 | ("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) same ("c4") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:06 |
| L8 | 0 | ("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) same c4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:06 |
| L9 | 0 | ("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) with c4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:07 |
| L10 | 93 | ("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and c4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:09 |
| L11 | 199 | ("257"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and c4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:07 |

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| L12 | 30 | 438/107,109,110,112,124,126, 127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and (c4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:09 |
| L13 | 2 | 438/107,109,110,112,124,126, 127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and (c4 adj (process or method)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:09 |
| L14 | 8 | ("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:21 |
| L15 | 15 | ("257"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:21 |
| L16 | 11 | ("257"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method)) | USPAT | OR | ON | 2005/05/31 12:21 |
| L17 | 6 | ("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method)) | USPAT | OR | ON | 2005/05/31 12:22 |
| S1 | 1 | ("20040180471").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/12/21 14:40 |
| S2 | 993 | (438/107).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/12/23 10:50 |
| S3 | 598 | (438/109).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 12:41 |

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| S4 | 469 | (438/112).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 12:41 |
| S5 | 767 | (438/124).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 12:41 |
| S6 | 750 | (438/126).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 12:41 |
| S7 | 1104 | (438/127).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 12:41 |
| S8 | 973 | (438/618).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 12:41 |
| S9 | 556 | (438/666).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 12:41 |
| S10 | 321 | (438/617).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 12:42 |
| S11 | 342 | (438/110).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/27 12:30 |

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| S12 | 13 | semiconductor same stack\$5 same lead same (flux or reflow or encapsul\$6) same solder same ((heat adj treat\$6) or temperature) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/27 09:59 |
| S13 | 2 | semiconductor with stack\$5 with lead with (flux or reflow or encapsul\$6) with solder with ((heat adj treat\$6) or temperature) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/27 08:15 |
| S16 | 2528 | semiconductor and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/27 11:47 |
| S17 | 343 | 438/107,109,110,112,124,126,127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/05/31 12:01 |
| S18 | 422 | 257/685,686,784,786,773,777,723.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/27 12:57 |
| S19 | 1 | ("20040157374").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/12/22 12:55 |
| S20 | 2 | ("6656840").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/12/27 09:48 |
| S22 | 47 | (anisotropic adj conduct\$5 adj adhesive) same (chip or die or ((integrated adj circuit) or ("IC"))) same (solder adj ball) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/27 06:42 |
| S23 | 5 | (anisotropic adj conduct\$5 adj adhesive) with fold\$6 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/09/27 06:44 |

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| S24 | 14 | (anisotropic adj conduct\$5 adj adhesive) same fold\$6 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/12/23 10:48 |
| S26 | 1 | ("6790710").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/27 10:10 |
| S30 | 5 | ((("5523605") or ("20040152290") or ("6683350"))).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/27 12:37 |
| S31 | 2 | ("5523605").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/27 12:33 |
| S32 | 4 | ((("5523605") or ("20040152290"))).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/27 12:37 |
| S36 | 2 | ((("6836006") or ("20020043708"))).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/12/22 13:46 |
| S38 | 7 | (anisotropic adj conduct\$5 adj adhesive) with (semiconductor adj packag\$5) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/12/23 10:49 |
| S39 | 1068 | (438/107).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/12/23 10:50 |
| S40 | 71 | 438/107,109,110,112,124,126,127,612,618,617,666.ccls. and (anisotropic adj conduct\$5 adj adhesive) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/12/23 10:52 |

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| S42 | 5 | (("6300679") or ("6737300") or ("6635968") or ("6620652") or ("6582992")).PN. | USPAT | OR | OFF | 2004/12/27 09:48 |
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